

ON Semiconductor®

FDB8832-F085

N-Channel Logic Level PowerTrench® MOSFET 30V, 80A, 2.1m Ω

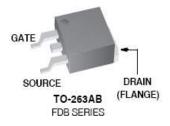
Features

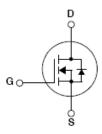
- Typ $r_{DS(on)} = 1.5m\Omega$ at $V_{GS} = 5V$, $I_D = 80A$
- Typ $Q_{g(5)} = 100nC$ at $V_{GS} = 5V$
- Low Miller Charge
- Low Q_{rr} Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant



Applications

- 12V Automotive Load Control
- Starter / Alternator Systems
- Electronic Power Steering Systems
- ABS
- DC-DC Converters





MOSFET Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	±20	V
	Drain Current Continuous (T _C < 165°C, V _{GS} = 10V)	80	
	Drain Current Continuous (T _C < 163°C, V _{GS} = 5V)	80	Α
I _D	Drain Current Continuous ($T_{amb} = 25^{\circ}C$, $V_{GS} = 10V$, with $R_{\theta JA} = 43^{\circ}C/W$)	34	_ ^
	Pulsed	See Figure 4	
E _{AS}	Single Pulse Avalanche Energy (Note 1)	1246	mJ
В	Power Dissipation	300	W
P_D	Derate above 25°C	2	W/°C
T_J , T_{STG}	Operating and Storage Temperature	-55 to +175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 2)	62	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, lin ² copper pad area		43	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB8832	FDB8832-F085	TO-263AB	330mm	24mm	800 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	racteristics					
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30	-	-	V
1	Zero Gate Voltage Drain Current	V _{DS} = 24V	-	-	1	μА
IDSS	Zero Gate Voltage Drain Current	$V_{GS} = 0V$ $T_J = 150^{\circ}C$	=	-	250	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0	1.6	3.0	٧
r _{DS(on)}	Drain to Source On Resistance	$I_D = 80A, V_{GS} = 10V$	•	1.4	1.9	
		$I_D = 80A, V_{GS} = 5V$	•	1.5	2.1	
		$I_D = 80A, V_{GS} = 4.5V$	-	1.6	2.2	mΩ
		I _D = 80A, V _{GS} = 10V T _J = 175°C	-	2.3	3.0	

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz		=	11400	-	pF
C _{oss}	Output Capacitance			=	2140	-	рF
C _{rss}	Reverse Transfer Capacitance			-	1260	-	pF
R_{G}	Gate Resistance	$V_{GS} = 0.5V$, $f = 1MHz$		-	1.2	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V		-	204	265	nC
Q _{g(5)}	Total Gate Charge at 5V	$V_{GS} = 0 \text{ to } 5V$ $V_{GS} = 0 \text{ to } 1V$ $V_{DD} = 15V$	-	100	130	nC	
$Q_{g(TH)}$	Threshold Gate Charge		-	10.9	14.2	nC	
Q_{gs}	Gate to Source Gate Charge		$I_{D} = 80A$ $I_{G} = 1.0 \text{mA}$	-	33	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau	.g	-	22	-	nC	
Q_{gd}	Gate to Drain "Miller" Charge			-	43	-	nC

Electrical Characteristics T	₁ = 25°C unless otherwise noted
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Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Switchi	ng Characteristics					
t _(on)	Turn-On Time		-	-	155	ns
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 15V, I_{D} = 80A$ $V_{GS} = 5V, R_{GS} = 1.5\Omega$	-	24	-	ns
t _r	Turn-On Rise Time		-	73	-	ns
t _{d(off)}	Turn-Off Delay Time		-	54	-	ns
t _f	Turn-Off Fall Time		-	38	-	ns
t _{off}	Turn-Off Time		-	-	149	ns

Drain-Source Diode Characteristics

V _{SD}	Source to Drain Diode Voltage	I _{SD} = 75A	-	0.8	1.25	V
	Source to Drain blode Voltage	I _{SD} = 40A	-	0.8	1.0	٧
t _{rr}	Reverse Recovery Time	$I_F = 75A$, di/dt = 100A/ μ s	-	59	77	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 75A$, di/dt = 100A/ μ s	-	67	87	nC

Notes: 1: Starting $T_J = 25^{\circ}C$, L = 0.61mH, $I_{AS} = 64$ A, $V_{DD} = 30$ V, $V_{GS} = 10$ V. 2: Pulse width = 100s.

Figure 1. Normalized Power Dissipation vs Case Temperature

T_C, CASE TEMPERATURE(°C)

Figure 2. Maximum Continuous Drain Current vs Case Temperature

T_C, CASE TEMPERATURE(°C)

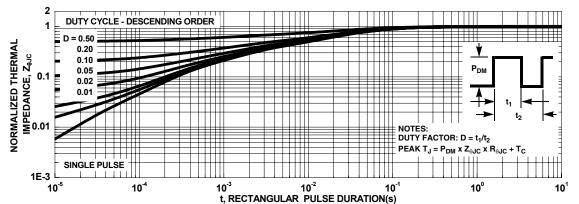


Figure 3. Normalized Maximum Transient Thermal Impedance

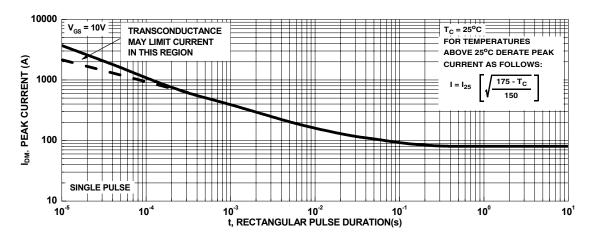


Figure 4. Peak Current Capability

Typical Characteristics

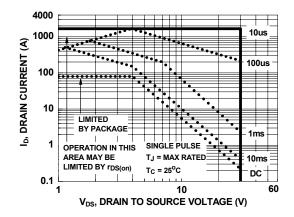


Figure 5. Forward Bias Safe Operating Area

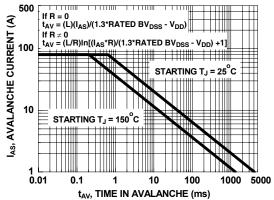


Figure 6. Unclamped Inductive Switching Capability

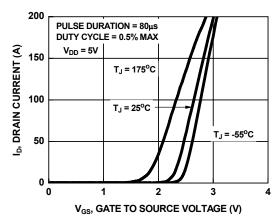


Figure 7. Transfer Characteristics

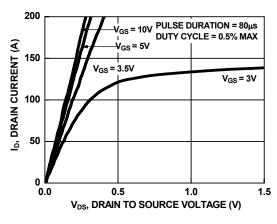


Figure 8. Saturation Characteristics

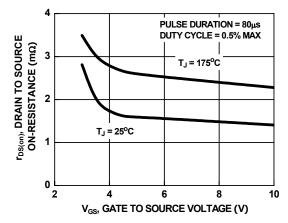


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

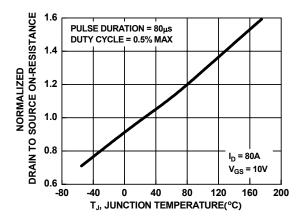


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

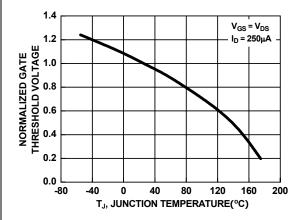
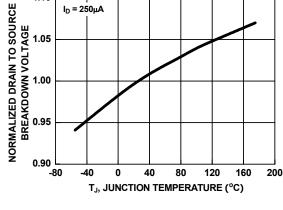


Figure 11. Normalized Gate Threshold Voltage vs
Junction Temperature



1.10

Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

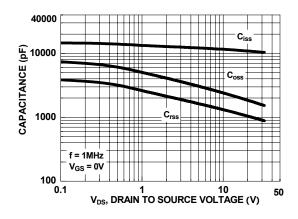


Figure 13. Capacitance vs Drain to Source Voltage

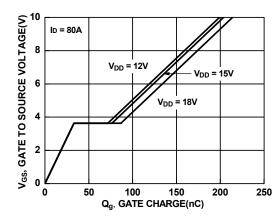


Figure 14. Gate Charge vs Gate to Source Voltage

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